

### Amendment to the Claims

#### **1-8. (Cancelled)**

9. (Currently Amended) An electroless plating method comprising:

positioning a substrate such that a surface thereof, to be plated, is directed downwardly;

flowing an electroless plating treatment liquid as a laminar flow along a bottom surface of a plating chamber, wherein the bottom surface of the plating chamber spreads upwardly and outwardly so as to define a quadratic curve in vertical section ~~quadratic-curved surface of a plating chamber so as to remove gas generated on the surface to be plated, the quadratic-curved surface spreading upwardly and outwardly;~~

bringing the surface to be plated into contact with the electroless plating treatment liquid in the plating chamber; and

processing the surface to be plated by the electroless plating treatment liquid in the plating chamber.

10. (Previously Presented) The electroless plating method according to claim 9, further comprising heating the electroless plating treatment liquid on a bottom of said plating chamber.

11. (Previously Presented) The electroless plating method according to claim 9, further comprising heating the substrate before the operation of bringing the surface to be plated into contact with the electroless plating treatment liquid in the plating chamber.

12. (Previously Presented) The electroless plating method according to claim 11, wherein said heating operation comprises heating the substrate to a temperature equal to a temperature of the electroless plating treatment liquid.

13.(Previously Presented) The electroless plating method according to claim 9, wherein said flowing operation comprises flowing the electroless plating treatment liquid in the plating chamber at a flow rate of 1 to 30 l/min.